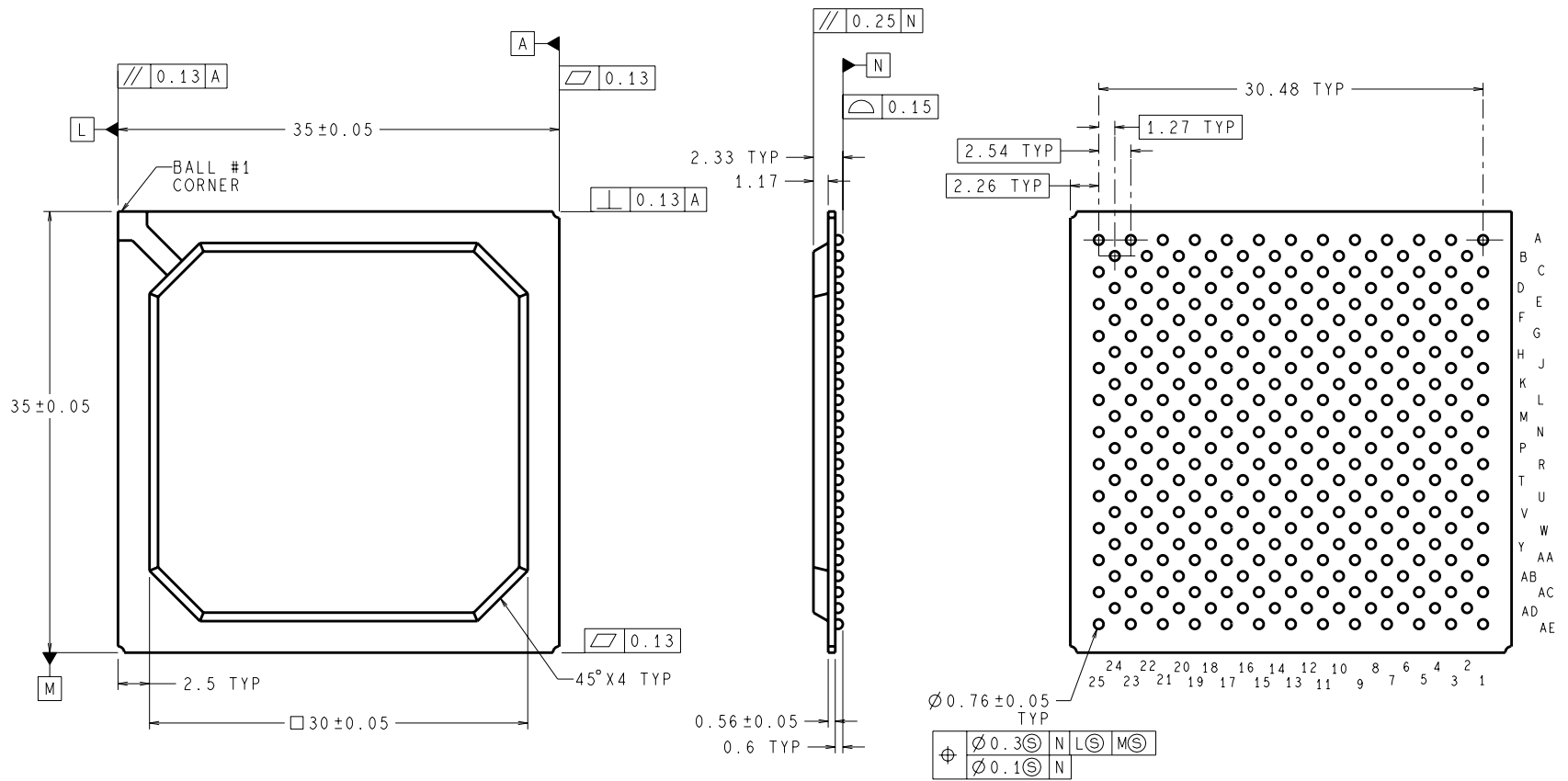


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL.	10386	06/07/94	DEG/SL
B	REVISE TITLE & NOTE 2; UPDATE DATUMS.	12229	05/27/1999	MS/



**DIMENSIONS ARE IN MILLIMETERS**

NOTES: UNLESS OTHERWISE SPECIFIED

1. SOLDER BALL COMPOSITION: Sn 63%, Pb 37%.
2. REFERENCE JEDEC REGISTRATION MO-151 VARIATION -1.27 PITCH, DATED JUNE 1997.

APPROVALS	DATE	NATIONAL SEMICONDUCTOR CORPORATION			
DRAWN <i>D. E. Grady</i>	06/07/1994	2900 Semiconductor Drive, Santa Clara, CA 95052-8090			
DFTG. CHK.		PBGA, 35 X 35 X 2.33mm, 313 BALL, 1.27mm PITCH			
ENGR. CHK.					
APPROVAL					
		SCALE	SIZE	DRAWING NUMBER	REV
		N/A	C	(SC)MKT-UCA313A	B
		DO NOT SCALE DRAWING		SHEET 1 of 1	